MICROCHIP

Semiconductor Device Type: **3BX_SOIC_8_3.90mm(.150in)_NiPdAu**

Sub-Component	Basic Substance	CAS Number	% Total Weight	mg/part	ppm
Mold Compound	Silica, Fused	60676-86-0	61.43	46.075	614339
Mold Compound	Epoxy Resin	Trade Secret	3.50	2.627	35025
Mold Compound	Epoxy, Cresol Novolac	29690-82-2	1.40	1.051	14010
Mold Compound	Phenol Resin	Trade Secret	3.50	2.627	35025
Mold Compound	Carbon Black	1333-86-4	0.21	0.158	2102
Lead Frame	Copper	7440-50-8	26.84	20.131	268408
Lead Frame	Iron	7439-89-6	0.04	0.030	404
Lead Frame	Phosphorous	7723-14-0	0.01	0.008	108
Lead Frame	Zinc	7440-66-6	0.01	0.006	81
Die Attach	Silver	7440-22-4	0.08	0.063	840
Die Attach	Epoxy Resin	Trade Secret	0.01	0.004	50
Die Attach	Cashew, nutshell liq. Polymer with epichlorohydrin	68413-24-1	0.01	0.004	50
Die Attach	Toluene	108-88-3	0.01	0.004	50
Die Attach	2-Heptyl-3,4-bis(9-isocyanatononyl)-1- pentylcyclohexane	68239-06-5	0.00	0.000	5
Die Attach	1,1'-(methylenedi-p-phenylene)bismaleimide	13676-54-5	0.00	0.000	5
Die	Silicon	7440-21-3	0.95	0.713	9500
Wire Bond	Gold	7440-57-5	0.50	0.375	5000
Plating	Nickel	7440-02-0	1.39	1.043	13905
Plating	Palladium	7440-05-3	0.10	0.073	975
Plating	Gold	7440-57-5	0.01	0.009	120
		TOTALS:	**100.00**	**75.00**	**1,000,000**

75.00 mg Total Mass

Package Homogeneous Materials

52.54	**(mg) Total**	**Mold Compound**	**% of Total Weight**	**70.05**
	Silica, Fused	60676-86-0	87.70	
	Epoxy Resin	Trade Secret	5.00	
	Epoxy, Cresol Novolac	29690-82-2	2.00	
	Phenol Resin	Trade Secret	5.00	
	Carbon Black	1333-86-4	0.30	
		Total	**100.00**	
20.18	**(mg) Total**	**Lead Frame**	**% of Total Weight**	**26.90**
	Copper	7440-50-8	99.78	
	Iron	7439-89-6	0.15	
	Phosphorous	7723-14-0	0.04	
	Zinc	7440-66-6	0.03	
		Total	**100.00**	
0.08	**(mg) Total**	**Die Attach**	**% of Total Weight**	**0.10**
	Silver	7440-22-4	84.00	
	Epoxy Resin	Trade Secret	5.00	
	Cashew, nutshell liq. Polymer with epichlorohydrin	68413-24-1	5.00	
	Toluene	108-88-3	5.00	
	2-Heptyl-3,4-bis(9-isocyanatononyl)-1- pentylcyclohexane	68239-06-5	0.50	
	1,1'-(methylenedi-p-phenylene)bismaleimide	13676-54-5	0.50	
		Total	**100.00**	
0.71	**(mg) Total**	**Die**	**% of Total Weight**	**0.95**
	Silicon	7440-21-3	100.00	
		Total	**100.00**	
0.38	**(mg) Total**	**Wire Bond**	**% of Total Weight**	**0.50**
	Gold	7440-57-5	100.00	
		Total	**100.00**	
1.13	**(mg) Total**	**Plating**	**% of Total Weight**	**1.50**
	Nickel	7440-02-0	92.70	
	Palladium	7440-05-3	6.50	
	Gold	7440-57-5	0.80	
75.00		**Total**	**100.00**	100.00

The information contained in this Material Content Declaration (MCD) consists of package-level information and is not part number specific. This information is considered to be sufficiently representative of all part numbers for the package type.

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